

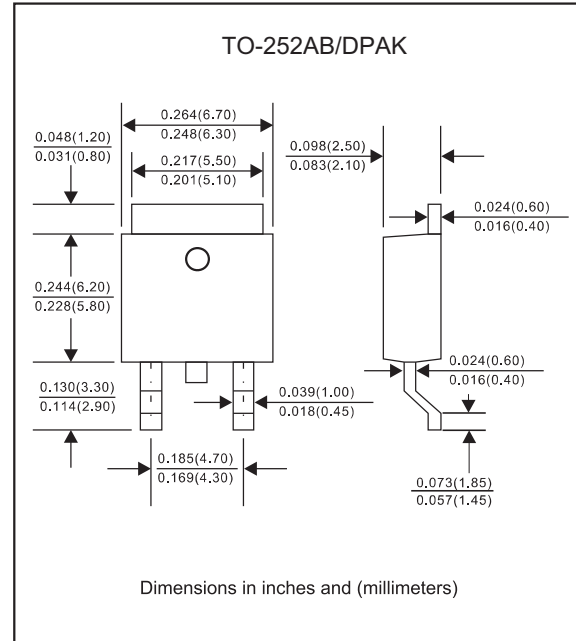
### Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- High surge capability.
- Guardring for overvoltage protection.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- Compliant to Halogen-free

### Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, TO-252AB/DPAK
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	$I_o$			30.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	$I_{FSM}$			175	A
Reverse current	$V_R = V_{RRM}$ $T_J = 25^\circ\text{C}$	$I_R$			0.5	mA
	$V_R = V_{RRM}$ $T_J = 125^\circ\text{C}$				50	
Thermal resistance (1)	Junction to case	$R_{\theta JC}$		6		$^\circ\text{C/W}$
Storage temperature		$T_{STG}$	-55		+150	$^\circ\text{C}$

NOTE : (1) Device mounted on additional heatsink, (50mm x 50mm x 23mm Al heatsink).

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	Operating temperature $T_J$ , ( $^\circ\text{C}$ )
MBR3040CD	40	28	40	0.70	
MBR3045CD	45	31.5	45		
MBR3060CD	60	42	60	0.80	
MBR30100CD	100	70	100		
MBR30150CD	150	105	150	0.95	
MBR30200CD	200	140	200		

\*1 Repetitive peak reverse voltage

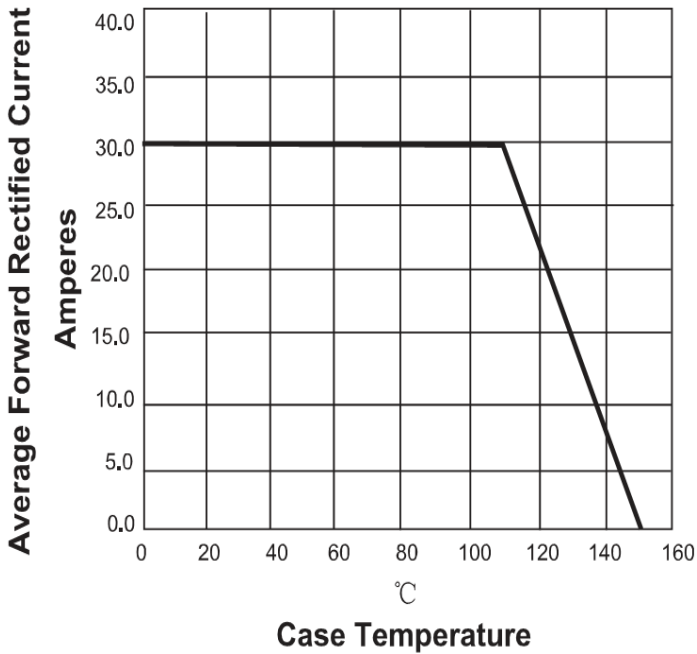
\*2 RMS voltage

\*3 Continuous reverse voltage

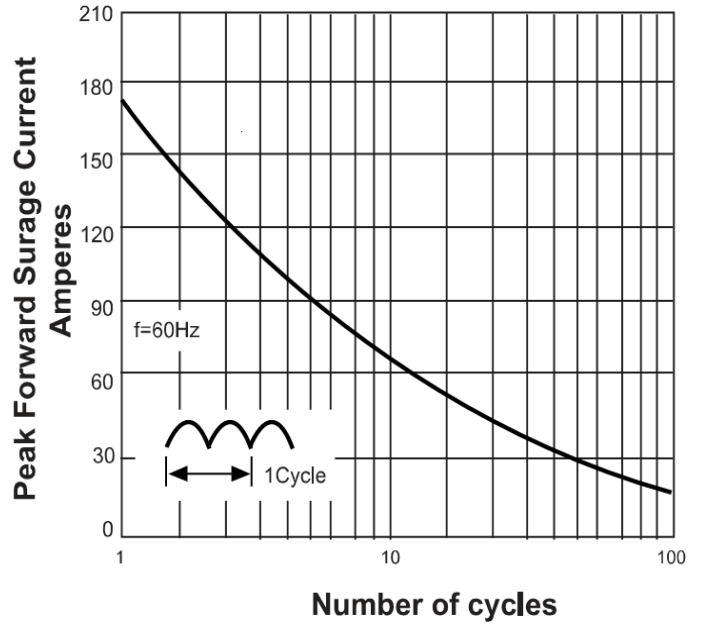
\*4 Maximum forward voltage  
IF = 15.0A, 25°C

## Rating and characteristic curves (MBR3040CD THRU MBR30200CD)

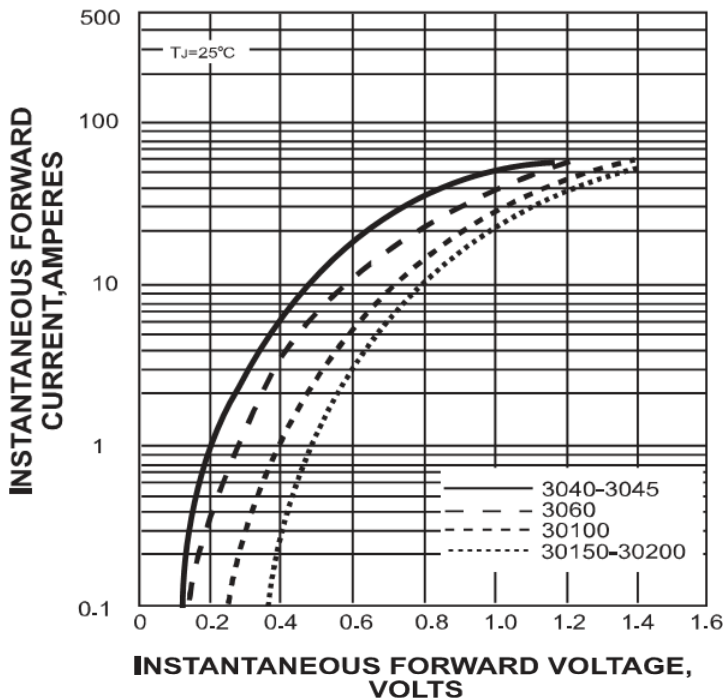
**FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT**



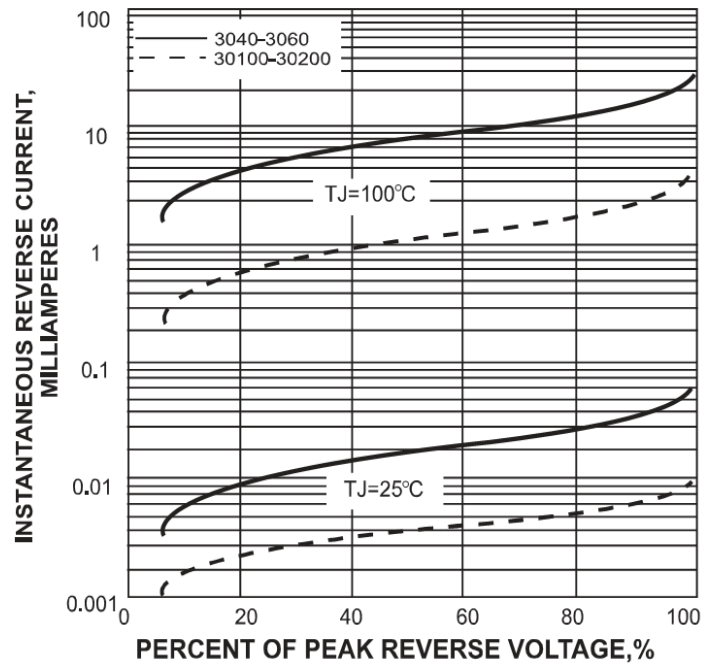
**FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG**



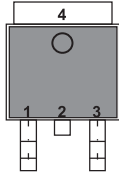
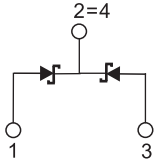
**FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS**



**FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS**



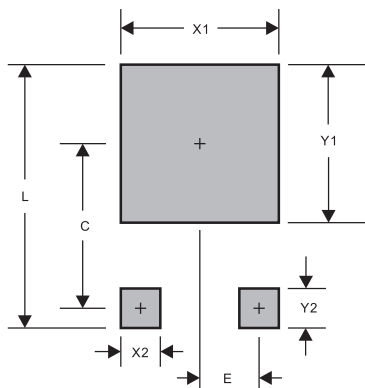
### Pinning information

Pin	Simplified outline	Symbol
Pin1 anode Pin2=4 cathode Pin3 anode		

### Marking

Type number	Marking code
MBR3040CD	SK3040
MBR3045CD	SK3045
MBR3060CD	SK3060
MBR30100CD	SK30100
MBR30150CD	SK30150
MBR30200CD	SK30200

### Suggested solder pad layout



PACKAGE	DPAK
C	0.272(6.90)
E	0.091(2.30)
L	0.457(11.60)
X1	0.276(7.00)
X2	0.059(1.50)
Y1	0.276(7.00)
Y2	0.098(2.50)

Dimensions in inches and (millimeters)